



Product/Process Change Notice - PCN 16_0235 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: Assembly Transfer to ASE Korea and Test Transfer to STATS ChipPAC Singapore of Select LFCSP Parts.

Publication Date: 09-Dec-2016

Effectivity Date: 19-Jan-2017 *(the earliest date that a customer could expect to receive changed material)*

Revision Description:

Included Test Correlation Results.

Description Of Change

ADI is transferring to subcontractor ASE Korea for assembly manufacturing and STATS ChipPAC Singapore for test manufacturing of select LFCSP products.
ADI has qualified ASE Korea's BOM(Bill of Materials). The mold compound is changing from Sumitomo G770 to Sumitomo G700. Die attach epoxy is changing from Able8290 and Able3230 to EN4900GC for 5x5 LFCSP devices. See BOM attachment for details.
The package outline exposed pad dimensions are changing for 3x3mm 8LD/16LD, 4x4mm 20LD/24LD, 5x5mm 28LD/32LD. See POD attachment for details.

Reason For Change

ADI's current Assembly and Test supplier STATS ChipPAC China is relocating their factory by end of September 2017. In this regard, the affected products currently assembled and tested in that facility will be transferred to new Assembly and Test site to ensure continuous supply of products.
ADI's assembly subcontractors manufacture products using Analog Devices specified manufacturing flows, materials, process controls and monitors, ensuring the same level of quality and reliability on products they receive from the new site.

Impact of the change (positive or negative) on fit, form, function & reliability

There will be no impact on the form, fit, function and reliability of the devices.

Product Identification *(this section will describe how to identify the changed material)*

The parts that will be assembled and tested from the new site will be identified by assembly lot and the country of origin.

Summary of Supporting Information

Qualification has been performed per ADI0012, Procedure for Qualification of New or Revised Processes. See attached Qualification Results Summary. Test correlation and validation has been performed per ADI's standard product site to site change correlation procedure. See attached Test Correlation Report.

Comments

During transition to new assembly and/or Test Site, products will be Assembled/or Tested from either current or new Assembly and/or Test Site. The customers may receive products that are assembled at AEK & tested at SCC and/or assembled at SCC & tested at STA.
Applies for all packing/reel options.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_16_0235_Rev_A_Qual Results Summary.pdf

Attachment 2: Type: Detailed Change Description

ADI_PCN_16_0235_Rev_A_BOM Change Description.pptx

Attachment 3: Type: Detailed Change Description

ADI_PCN_16_0235_Rev_A_POD Change Description.pptx

Attachment 4: Type: Test Correlation Report

ADI_PCN_16_0235_Rev_A_TEST CORRELATION RESULT.xlsx

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models**Existing Parts - Product Family / Model Number (21)**

AD5541A / AD5541ABCPZ-1-RL7	ADA4096-4 / ADA4096-4ACPZ-R7	ADA4096-4 / ADA4096-4ACPZ-RL	ADA4500-2 / ADA4500-2ACPZ-R7	ADA4500-2 / ADA4500-2ACPZ-RL
ADM1075 / AD51095Z-0RL7	ADM1075 / ADM1075-1ACPZ	ADM1075 / ADM1075-1ACPZ-RL7	ADM1075 / ADM1075-2ACPZ	ADM1075 / ADM1075-2ACPZ-RL7
ADP1051 / AD80393ACPZ-R7	ADP1051 / ADP1051ACPZ-R7	ADP1051 / ADP1051ACPZ-RL	ADP1850 / ADP1850ACPZ-R7	ADP323 / ADP323ACPZ-R7
ADP5134 / ADP5134ACPZ-R7	ADP7182 / ADP7182ACPZ-5.0-R7	ADP7182 / ADP7182ACPZ-R7	SSM2518 / SSM2518CPZ	SSM2518 / SSM2518CPZ-R7
SSM2518 / SSM2518CPZ-RL				

Appendix B - Revision History

Rev	Publish Date	Effectivity Date	Rev Description
Rev. -	21-Oct-2016	19-Jan-2017	Initial Release
Rev. A	09-Dec-2016	19-Jan-2017	Included Test Correlation Results.

Analog Devices, Inc.

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